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SUZUKI ISATO(54) DIE OF MOLDED COIL, AND METHOD FOR  
MANUFACTURING MOLDED COIL

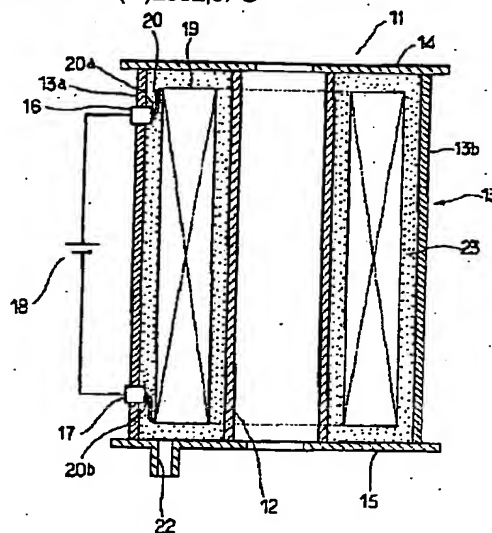
## (57) Abstract

**PROBLEM TO BE SOLVED:** To prevent to the utmost current from flowing through a thermosetting resin, when a molded coil is manufactured by charging the thermosetting resin into the die body in which the coil is incorporated, energizing the coil conductor and curing the thermosetting resin, by making the coil conductor generating heat.

**SOLUTION:** A separated die 13a, which is a region of the die body 11 where conducting terminals 16 and 17 are provided is formed of an insulating material. After incorporating the coil 19 in the die body 11 and charging the thermosetting resin 23 into the die body 11, direct current is made to flow through the coil conductor 20 via the conducting terminals 16 and 17. Then the coil conductor 20 generates heat, and the thermosetting resin 23 is heated. In this case, since no conductive material exists near both ends 20a and 20b of the coil conductor 20 whose metal surface is exposed, current will not flow through the thermosetting resin 23. Accordingly, inhibition of curing can be prevented,

and the thermosetting resin 23 can be cured properly.

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11: 金型本体  
16, 17: 通電端子  
18: コイル  
20: コイル導体  
20a, 20b: コイル導体の端部  
21: 出入口  
22: 熱硬化性樹脂